TOSHIBA Schottky Barrier Diode

CMS16

Switching Mode Power Supply Applications Portable Equipment Battery Applications **DC-DC Converter Applications**

Repetitive peak reverse voltage $: V_{RRM} = 40 \text{ V}$ Average forward current $: I_{F}(AV) = 3 A$

 $: V_{FM} = 0.55 \text{ V (max) (@I_{FM} = 3 \text{ A)}}$ Peak forward voltage Suitable for compact assembly due to a small surface-mount package: "M-FLATTM" (Toshiba package name)"

Absolute Maximum Ratings (Ta = 25°C)

Characteristic	Symbol	Rating	Unit
Repetitive peak reverse voltage	V _{RRM}	40	V
Average forward current	IF (AV)	3 (Note 1)	Α
Non-repetitive peak forward surge current	I _{FSM}	30 (50 Hz)	Α
Junction temperature	Tj	-40 to 150	°C
Storage temperature range	T _{stg}	-40 to 150	°C

Note 1: T\(= 106°C Device mounted on a ceramic board

Board size : 50 mm × 50 mm Soldering land size : $2 \text{ mm} \times 2 \text{ mm}$ Board thickness : 0.64 mm

Rectangular waveform ($\alpha = 180^{\circ}$), VR = 20 V

Note 2: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the

reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Electrical Characteristics (Ta = 25°C)

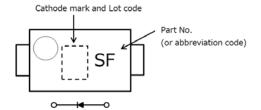
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Dook forward valtage	V _{FM (1)}	I _{FM} = 1 A (pulse test)	_	0.4	_	V
Peak forward voltage	V _{FM (2)}	I _{FM} = 3 A (pulse test)	_	0.50	0.55	
Dook ropotitivo rovorgo gurrent	IRRM (1)	V _{RRM} = 5 V (pulse test)	_	2	_	μΑ
Peak repetitive reverse current	IRRM (2)	V _{RRM} = 40 V (pulse test)	_	26	200	
Junction capacitance	Cj	V _R = 10 V, f = 1 MHz	_	95	_	pF
Thermal resistance (junction to ambient)	Rth (j-a)	Device mounted on a ceramic board board size : 50 mm × 50 mm soldering land size : 2 mm × 2 mm board thickness : 0.64 mm	_	_	60	
		Device mounted on a glass-epoxy board board size : 50 mm × 50 mm soldering land size : 6 mm × 6 mm board thickness : 1.6 mm	_	_	135	°C/W
		Device mounted on a glass-epoxy board board size : 50 mm × 50 mm soldering land size : 2.1 mm × 1.4 mm board thickness : 1.6 mm	_	_	210	
Thermal resistance (junction to lead)	Rth (j-l)	_	_	_	16	°C/W

Start of commercial production

Weight: 0.023 g (typ.)

Marking

Abbreviation Code	Part No.		
SF	CMS16		



Land pattern dimensions for reference only

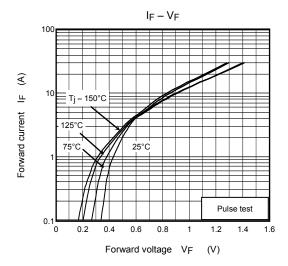
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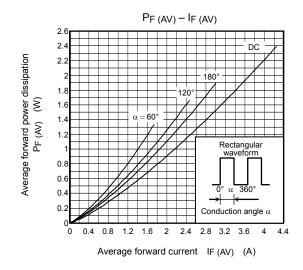


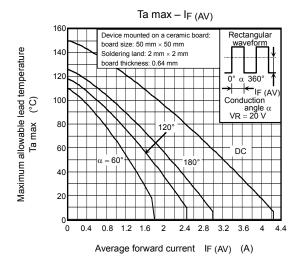
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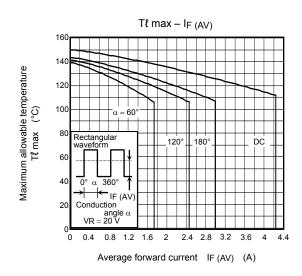
Handling Precaution

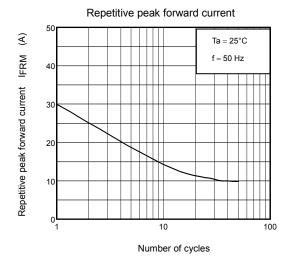
- 1) Schottky barrier diodes (SBDs) have reverse current greater than other types of diodes. This makes SBDs more vulnerable to damage due to thermal runaway under high-temperature and high-voltage conditions. Thus, both forward and reverse power losses of SBDs should be considered for thermal and safety design.
- 2) The absolute maximum ratings are rated values that must not be exceeded during operation, even for an instant. The following are the recommended general derating methods for designing a circuit board using this device.
 - V_{RRM}: Use this rating with reference to 1) above. V_{RRM} has a temperature coefficient of 0.1%/°C at low temperatures. Take this coefficient into account when designing a circuit board that will be operated in a low-temperature environment.
 - I_{F(AV)}: We recommend that the worst-case current be no greater than 80% of the absolute maximum rating of I_{F(AV)} and that the worst-case junction temperature, T_j, be kept below 120°C. When using this device,
 - allow margins, referring to the T_{a(max)}-I_{F(AV)} curve.
 - I_{FSM}: This rating specifies peak non-repetitive forward surge current. This only applies to an abnormal operation, which seldom occurs during the lifespan of a device.
 - T_j: Derate device parameters in proportion to this rating in order to ensure high reliability. We recommend that the junction temperature (T_j) of a device be kept below 120°C.
- 3) Thermal resistance (junction-to-ambient) varies with the mounting conditions of a device on a circuit board. An appropriate thermal resistance value should be used, considering the heatsink, circuit board design and land pattern dimensions (provided for reference only).
- 4) For other design considerations, see the Rectifiers databook or the Toshiba website.

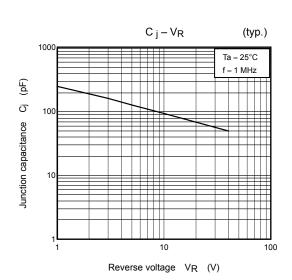


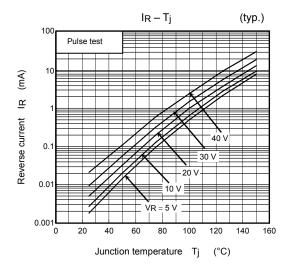


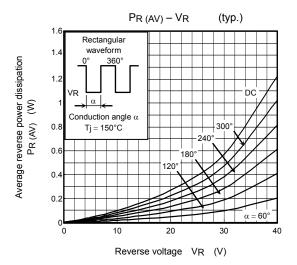


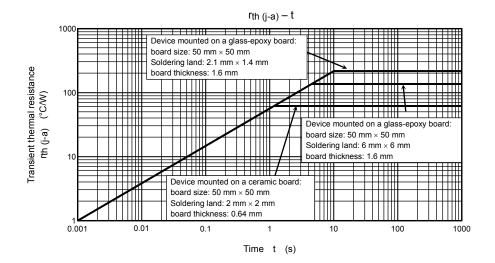












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